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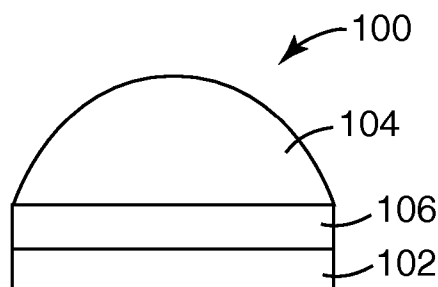
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(54) Title: OPTICAL BONDING COMPOSITION FOR LED LIGHT SOURCE



(57) Abstract: An optical bonding composition and LED light source comprising the composition are disclosed, as well as a method of making the LED light source. The LED light source may comprise: an LED die; an optical element optically coupled to the LED die; and a bonding layer comprising an amorphous organopolysiloxane network, the organopolysiloxane network comprising a silsesquioxane portion derived from $(R^1SiO_{1.5})_n$ wherein R^1 is an organic group and n is an integer of at least 10; the bonding layer bonding the LED die and the optical element together. Efficiency of the LED light source may be increased when using an optical extractor as the optical element.

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OPTICAL BONDING COMPOSITION FOR LED LIGHT SOURCE

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CROSS REFERENCE TO RELATED APPLICATION

This application claims the benefit of U.S. Provisional Patent Application No. 60/866448, filed November 20, 2006, the disclosure of which is incorporated herein by reference in its entirety.

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FIELD OF THE INVENTION

The invention relates to LED light sources, and particularly, to an LED light source having an optical element bonded to an LED die using an optical bonding composition.

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BACKGROUND

LED light sources have the inherent potential to provide the brightness, output, and operational lifetime of conventional light sources. Unfortunately, an LED light source produces light in a semiconductor material, often referred to as an LED die, and it can be difficult to extract light efficiently from the LED die without substantially reducing brightness or increasing the apparent emitting area of the LED light source. This difficulty is often due to the large refractive index mismatch between the LED die (refractive index, n , 2.4 or greater) and air ($n = 1$) such that much of the light generated in the LED die is totally internally reflected and cannot escape the die thus reducing brightness.

25

Previous approaches for extracting light from LED dies include the use of encapsulants which encapsulate the LED die. Encapsulants typically have a higher refractive index than air ($n \sim 1.5$ for typical epoxy encapsulants) such that the refractive index mismatch at the interface of the die with its surroundings is reduced. As a result, less light is wasted and the light source is brighter. There is, however, need for further improvement in efficiency and brightness. In addition, encapsulants are susceptible to large temperature shifts from heat generated at the LED die which causes stress that can

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damage the die over many temperature cycles. Encapsulants can also yellow and otherwise degrade over time.

Extractors may also be used to extract light from LED dies. These optical elements are typically transparent polymers or glasses and are disposed in contact with or in close proximity to the surface of the LED die. The extractor and LED die are optically coupled such that light is extracted from the LED die. Extractors typically have an input surface sized and shaped to substantially mate with a major emitting surface of the LED die. The use of extractors, however, has been hampered by the difficulty with bonding the extractor and the LED die. Known bonding methods require elevated temperatures (greater than 350°C) and pressures, both of which may negatively affect the functionality of the LED light source. Known bonding methods also require involved manufacturing processes, such as chemical vapor deposition, various forms of epitaxy, etc., which limits the usefulness of these methods to select applications.

SUMMARY

Disclosed herein is an optical bonding composition and an LED light source comprising the composition. The LED light source may comprise: an LED die; an optical element optically coupled to the LED die; and a bonding layer comprising an amorphous organopolysiloxane network, the organopolysiloxane network comprising a silsesquioxane portion derived from



wherein R^1 is an organic group and n is an integer of at least 10; the bonding layer bonding the LED die and the optical element together.

The amorphous organopolysiloxane network may comprise surface-modified metal oxide nanoparticles comprising metal oxide nanoparticles and a surface-modifier. Useful metal oxide nanoparticles include zirconium oxide, titanium oxide, zinc oxide, tantalum oxide, niobium oxide, lanthanum oxide, strontium oxide, yttrium oxide, hafnium oxide, tin oxide, antimony oxide, and combinations thereof. Mixed oxides of the aforementioned may also be used. In one particular example, the metal oxide nanoparticles comprise crystalline zirconium oxide nanoparticles having a refractive index of greater than about 1.8. Useful surface-modifiers include carboxylic acids, phosphonic acids, alkoxy silanes, or a combination or mixture thereof.

The optical element is typically an optical extractor that increases efficiency of the light source by facilitating escape of light from inside the LED die.

Also disclosed herein is a method of making an LED light source using the optical bonding composition. The method comprises a) providing an LED die; b) providing an optical element; c) providing an optical bonding composition comprising a silsesquioxane having the formula $(R^1SiO_{1.5})_n(OR^4)_{n+2}$ and a dialkoxysilane having the formula $(R^2)_2Si(OR^3)_2$, wherein R^1 to R^4 are organic groups and n is an integer of at least 5; and d) bonding the LED die and the optical element together by contacting the LED die and the optical element with the optical bonding composition.

The LED light source disclosed herein may be useful in a variety of lighting applications such as for backlighting signs and liquid crystal displays that may be either edge-lit or direct-lit. The LED light source disclosed herein may also be used as a light source for LED signage, automotive applications, projection applications, and general illumination including architectural, mood, and artistic lighting.

These and other aspects of the invention will be apparent from the detailed description below. In no event, however, should the above summary be construed as a limitation on the claimed subject matter, which subject matter is defined solely by the attached claims, as may be amended during prosecution.

BRIEF DESCRIPTIONS OF DRAWINGS

The invention may be more completely understood in consideration of the following detailed description and examples in connection with the figures described below. The figures, in no event, should be construed as limitations on the claimed subject matter, which subject matter is defined solely by the claims as set forth herein.

FIG. 1 shows a schematic cross section of an exemplary LED light source.

FIGS. 2a-2d show exemplary converging extractors.

FIGS. 3a-3c and 4a-4b show exemplary diverging extractors.

DETAILED DESCRIPTION

FIG. 1 shows a schematic cross section of exemplary LED light source 100 comprising LED die 102 and optical element 104 that are bonded together by bonding layer 106. The bonding layer comprises surface-modified metal oxide nanoparticles in an

amorphous silicate network. In general, the LED die and the optical element are optically coupled such that light emitted by the LED die is able to propagate and reach the optical element. The optical element may be an extractor into which light can enter and exit in a variety of ways depending on the particular nature of the element.

5 For simplicity, the LED die is shown generically in FIG. 1 but can include conventional design features known in the art. For example, the LED die can include distinct p- and n-type semiconductor layers typically formed from III-V semiconductors including nitrides such as AlN, GaN, InN; phosphides such as InGaP, AlP, GaP, InP; and others such as AlAs, GaAs, InAs, AlSb, GaSb, and InSb. The LED die may also be
10 formed from a II-VI semiconductor such as ZnS, ZnSe, CdSe, and CdTe; Group IV semiconductors Ge, Si and carbides such as SiC. The LED die may also comprise buffer layers, substrate layers, and superstrate layers. The refractive index of an LED die ranges from about 1.7 to about 4.1 at the typical emission wavelength of the light source in which it is present.

15 Although a rectangular LED die is shown, other known configurations are also contemplated, such as an LED die with angled side surfaces that form a truncated inverted pyramid. Electrical contacts to the LED die are not shown for simplicity but can be provided on any one or more surfaces for application of power to energize the device. Examples include solder reflow, wire bonding, tape automated bonding (TAB), or flip-
20 chip bonding. The individual layers and other functional elements of the component or chip are typically formed on the wafer scale, and the finished wafer can then be diced into individual piece parts to yield a multiplicity of LED dies. The LED die may be configured for surface mount, chip-on-board, or other known mounting configurations.

The optical elements disclosed herein are made of solid, transparent materials
25 having a relatively high refractive index. Suitable materials for optical elements include inorganic materials such as optical glasses, e.g. Schott glass type LASF35 or N-LAF34, available from Schott North America, Inc., and those described in US Ser. No. 11/381518 (Leatherdale et al.), the disclosure of which is incorporated herein by reference. Other suitable inorganic materials include ceramics, e.g. sapphire, zinc oxide, zirconium oxide,
30 diamond, and silicon carbide. Sapphire, zinc oxide, diamond, and silicon carbide are particularly useful since these materials also have a relatively high thermal conductivity (0.2 – 5.0 W/cm K). The optical element may also comprise thermoset high index

polymers such as acrylics, epoxies, silicones, polycarbonates and polycyclics, or thermoplastic high index polymers such as polycarbonates and cyclic olefins. The optical element may comprise a thermoset or thermoplastic polymer in combination with ceramic nanoparticles including zirconium oxide, zinc oxide, titanium oxide, and zinc sulfide.

5 The refractive index of the extractor may be at least about 1.5, for example, greater than about 1.8, or greater than about 2, at the emission wavelength of the LED die. In one example, the refractive index of the optical element may be the same as, nearly the same as, or no greater than that of the light emitting surface of the LED die. This would allow for maximum extraction of the light. For example, the refractive indices may be within
10 about 0.2. Alternatively, the refractive index of the extractor may be greater than or less than that of the light emitting surface of the LED die. For example, if the light emitting surface of the LED die is 1.75, then the extractor may have a refractive index of 1.7, 1.75, 1.9, 2.1, or 2.3.

 In one example, the optical element comprises an optical glass having a refractive
15 index of at least about 1.7. In another example, the optical element comprises a glass or glass-ceramic material having a refractive index of at least about 2.0, preferably at least 2.1, 2.2, or 2.3 or more, as described in US Ser. No. 11/381518 (Leatherdale et al.). In general, these materials comprise less than 20% by weight B_2O_3 , less than 20% by weight SiO_2 , and less than 40% by weight P_2O_5 . In some cases, the following materials are
20 limited to less than 20% by weight: As_2O_3 , Bi_2O_3 , GeO_2 , NaO , TeO_2 , V_2O_5 , SiO_2 , B_2O_3 , and P_2O_5 . Useful glasses or glass-ceramic materials comprise at least two metal oxides such as Al_2O_3 ; TiO_2 ; rare earth oxides; or alkaline earth metal oxides. The crystallization temperature T_x of these materials is preferably at least 5°C above their glass transition temperature T_g , which facilitates molding of the material into an optical element.

25 One example of an optical element is an extractor which can be used to extract light out of the LED die. In general, the extractor modifies the angular distribution of light, turning a first light emission pattern into a second, different light emission pattern. Depending on the shape of the extractor, the pattern of the emitted light is in a generally forward direction and may be circular around the extractor, or to the sides in some
30 symmetrical or asymmetrical distribution.

 The optical element may comprise a converging extractor as described in US Ser. No. 11/381324 (Leatherdale et al.), the disclosure of which is incorporated herein by

reference. Converging extractors have at least one converging side, a base, and an apex, the apex disposed at least partially over the base and having a surface area smaller than that of the base, and the at least one converging side converging from the base towards the apex. The shape of the converging extractor can be pyramidal, polyhedral, wedge-like, cone-like, etc., or some combination thereof. The base can have any shape, e.g., square, circular, symmetrical, non-symmetrical, regular, or irregular. The apex may be a point, a line, or a flat or rounded surface, and it resides over the base either centered or skewed away from the center of the base. For a converging extractor, the base is typically disposed adjacent and generally parallel to the LED die. Also, the base and the LED die may be substantially matched in size, or the base can be smaller or larger than the LED die.

FIGS. 2a-2d show perspective views of exemplary converging extractors: FIG. 2a shows a four-sided pyramid; FIG. 2b shows a six-sided polygon; and FIGS. 2c and 2d show wedges wherein the apex (a line) is disposed above the base, the apex centered and skewed away from the center, respectfully. The extractor shown in FIG. 2d also has two diverging sides which act to collimate the light and the converging sides allow the light to be redirected to the sides. Other examples of converging extractors are shown in US Application Ser. No. 11/381324 (Leatherdale et al.).

The optical element may comprise a diverging extractor as described in US Appl. Nos. 2006/0091784 A1 (Connor et al.), 2006/0091411 A1 (Ouderkirk et al.), 2006/0091798 A1 (Ouderkirk et al.), and 2006/0092532 A1 (Ouderkirk et al.), the disclosures of which are incorporated herein by reference. A diverging extractor has at least one diverging side, an input surface, and an output surface that is larger than an input surface. Diverging extractors are generally shaped in the form of a taper. FIGS. 3a-3c show exemplary diverging extractors: FIG. 3a shows a perspective view of a truncated inverted polygon having four sides; FIG. 3b shows a perspective view of a truncated inverted taper having parabolic sidewalls; and FIG. 3c shows a schematic cross section of a truncated inverted cone having a convex output surface.

Examples of diverging extractors are also shown in FIGS. 4a and 4b previously described in US Ser. No. 11/381518 (Leatherdale et al.). The surfaces of these extractors are arranged to redirect light from the LED die in a predominately sideways direction, rather than in a forward direction along a central axis of the LED die. Side-emitting LEDs

are particularly suited for use in thin direct-lit backlights for liquid crystal display panels, since the light can be made to spread out laterally over a short distance, avoiding bright and dark areas or hot spots across the viewing area of the display.

FIG. 4a is a schematic side view of a wedge-shaped extractor 400. Extractor 400
5 has an input surface 402, an output surface 404, and side surfaces 406a and 406b. The input and output surfaces may be disposed at a substantial angle to each other, nominally about 90 degrees. With this arrangement, light rays 408a entering through the input surface reflect off of one or both of the side surfaces (whether by total internal reflection or with the aid of a reflective material or coating, not shown) and are redirected
10 approximately sideways as represented by light rays 408b. Light rays 408b subsequently exit through the output surface. The shape or perimeter of extractor 400 from a top view may take any of a variety of forms including rectangular, trapezoidal, pie-shaped, semicircular or any combination thereof.

FIG. 4b is a schematic side view of another wedge-shaped extractor 410. Extractor
15 410 has an input surface 412, an output surface 414, and side surfaces 416. The extractor 410 can have the shape of extractor 400 rotated about a vertical axis coincident with side surface 406a. In some cases, the extractor can be made by joining two of the extractors 400 at their respective side surfaces 406a in a compound construction. In a different compound construction, phantom line 418 represents a possible interface or boundary
20 between distinct optical bodies making up the extractor 410.

Similar to extractor 400, the input and output surfaces of extractor 410 are disposed at a substantial angle to each other, nominally about 90 degrees. Light from the LED entering through the input surface reflect off of one or both side surfaces (whether by total internal reflection or with the aid of a reflective material or coating, not shown) and
25 are redirected approximately sideways, subsequently exiting through the output surface. From a top view (not shown), extractor 410 can have any of a number of shapes including, for example, polygonal (e.g. square or rectangular), circular, and elliptical. With circular and elliptical shapes or perimeters, light entering through the input surface is redirected to form a ring of output light.

30 As for converging extractors, the input surface of a diverging extractor is typically disposed closest and generally parallel to the LED die. Also, the input surface and the LED die may be substantially matched in size, or the input surface can be smaller or larger

than the LED die. Other examples of diverging extractors are described in US 7,009,213 B2 and US 6,679,621 B2.

As described above, the LED die comprises alternating semiconductor layers. One of the outermost layers may be referred to as a light emitting layer, and this layer has an outermost surface that may be referred to as a light emitting surface. Also as described above, the optical element comprises a light input surface. In one useful configuration, the LED light source comprises the LED die and the optical element bonded together such that the light emitting surface and the light input surface are in contact with the bonding layer as shown, for example, in FIG. 1.

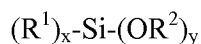
An optical bonding composition is used to form the bonding layer. The optical bonding composition comprises a silsesquioxane having the formula $(R^1SiO_{1.5})_n(OR^4)_{n+2}$ and a dialkoxysilane having the formula $(R^2)_2Si(OR^3)_2$, wherein R^1 to R^4 are organic groups and n is an integer of at least 5. R^1 may be an alkyl, alkylaryl, arylalkyl, aryl, alcohol, polyglycol, or polyether group, for example, a methyl, ethyl, propyl, phenyl or naphthyl group. R^1 and R^2 may be the same or different, and they may be independently selected from the group consisting of methyl, phenyl, combinations thereof, and mixtures thereof. For example, R^1 and R^2 may both comprise phenyl. R^3 and R^4 may be the same or different, and they may be independently selected from the group consisting of alkyl, acetoxy, and methoxyethoxy groups, and combinations thereof, and mixtures thereof. For example, R^3 and R^4 may both comprise methyl. Also, n may be at least 10, or at least 20.

A bonding layer between the LED die and the optical element is formed when the LED die and the optical element are bonded together. It is believed that the optical bonding composition undergoes reaction to form an amorphous organopolysiloxane network. The reaction may be accelerated by application of heat. An amorphous organopolysiloxane network refers to a chemical bond network derived from condensation of organosiloxane precursors. In one example, the amorphous organopolysiloxane network is derived essentially from D-units comprising: $(R^2)_2Si(OR^3)_2$.

Silsesquioxanes or polysilsesquioxanes are derived from fundamental molecular units that have silicon coordinated with three bridging oxygen atoms. Because of this, silsesquioxanes can form a wide variety of complex three-dimensional shapes. Various polysilsesquioxanes can be used, for example, polymethylsilsesquioxane, polyphenylsilsesquioxane and polymethylphenylsilsesquioxane. Suitable specific

polysilsesquioxanes include, but are not limited to, polymethylsilsesquioxane from Techneglas of Columbus, Ohio and sold under the label GR653L, GR654L, and GR650F; polyphenylsilsesquioxane from Techneglas of Columbus, Ohio and sold under the label GR950F; and polymethylphenylsilsesquioxane from Techneglas of Columbus, Ohio and
5 sold under the label GR908F.

The optical bonding composition may also comprise other alkoxysilanes, such as tetraalkoxysilanes and alkyltrialkoxysilanes having the formula:



wherein R^1 may be an alkyl, alkylaryl, arylalkyl, aryl, alcohol, polyglycol, or polyether
10 group, or a combination or mixture thereof; R^2 may be an alkyl, acetoxy, or a methoxyethoxy group, or a mixture thereof; x = from 0 to 3 and y = from 4 to 1 respectively, with the proviso that $x + y = 4$. The one or more alkoxysilanes including mono-, di-, tri-, and tetraalkoxysilanes may be added to control the crosslink density of the organosiloxane network and control the physical properties of the organosiloxane network
15 including flexibility and adhesion promotion. Examples of such alkoxysilanes include, but are not limited to, tetraethoxysilane, tetramethoxysilane, methytriethoxysilane, and methyltrimethoxysilane. Such ingredients may be present in an amount of about 0 to 50 weight percent.

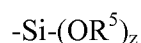
A variety of solvents can also be suitably used in the optical bonding composition
20 in order to lower the viscosity of the bonding composition in order to allow for the deposition of thinner layers of the bonding composition on either the LED emitting surface or optical element. Examples of such solvents include alcohols, ketones, ethers, acetates, and the like. Exemplary solvents include methanol, ethanol, butanol, and 1-methoxy-2-propanol. Aromatic solvents such as toluene, xylenes, and the like may be
25 useful for formulations which have aryl character in the silsesquioxane and the alkoxysilane.

Additives may be added to the optical bonding composition in order to increase adhesion to a substrate, modify flow properties to enhance coating of a substrate, or to catalyze the condensation reactions of the components in the composition to form the
30 organopolysiloxane network. Examples of suitable catalysts include acids, bases, and organic complexes of metals. In one particular example, the catalyst is an organic acid such as acetic acid.

The optical composition may also comprise surface-modified metal oxide nanoparticles. The surface-modified metal oxide nanoparticles may comprise metal oxide nanoparticles selected from the group consisting of zirconium oxide, titanium oxide, zinc oxide, tantalum oxide, niobium oxide, lanthanum oxide, strontium oxide, yttrium oxide, hafnium oxide, tin oxide, antimony oxide, and combinations thereof. The metal oxide nanoparticles may also comprise mixed metal oxide nanoparticles of at least two metal oxides selected from the group consisting of silicon oxide, aluminum oxide, zirconium oxide, titanium oxide, zinc oxide, tantalum oxide, niobium oxide, lanthanum oxide, strontium oxide, yttrium oxide, hafnium oxide, tin oxide, antimony oxide, and combinations thereof. Titanium oxide nanoparticles may be of the rutile or anatase form. Particular examples of mixed metal oxide nanoparticles include those comprising silicon oxide and zirconium oxide; silicon oxide and titanium oxide; and silicon oxide, zirconium oxide, and titanium oxide. The particular metal oxide nanoparticles used may depend on a variety of factors such as refractive index, compatibility in the optical composition, cost, etc.

The metal oxide nanoparticles are surface-modified with one or more surface modifiers in order to increase compatibility of the metal oxide nanoparticles with other components in the bonding layer and/or the optical composition. For example, zirconium oxide nanoparticles are stable in aqueous acidic environments having a pH of from 2 to 4, and surface-modification could be used to protect against flocculation of the nanoparticles in the aqueous basic environment of the optical composition. Surface modification involves reacting the metal oxide nanoparticles with the surface modifier(s) which attach to the surface of the nanoparticles and which modify the surface characteristics thereof.

Surface modifiers may be represented by the formula A-B where the A group is capable of attaching to the surface of the metal oxide nanoparticle, and the B group is a compatibilizing group. In general, the A group needs to be selected by considering the particular metal oxide and the nature of the optical composition, i.e., the surface-modified metal oxide nanoparticles should be stable such that compatibility is maintained in the highly basic environment. Useful A groups include carboxylic acids, phosphonic acids, alkoxysilanes, and combinations and mixtures thereof. Alkoxysilanes may be represented by the formula:



wherein R⁵ is an alkyl group, an acetoxy group, a methoxyethoxy group, or mixtures thereof; and z = from 1 to 3.

Useful B groups are hydrophilic groups that render the metal oxide nanoparticles compatible in the optical composition; examples include alcohols, polyglycols, and
5 polyethers and/or hydrophobic groups such as alkyl groups. Examples of surface modifiers include polyethyleneglycol alkoxysilanes and polyethyleneglycol-like carboxylic acid derivatives such as 2[-2-(2-methoxyethoxy)ethoxy]acetic acid and (2-methoxyethoxy)acetic acid.

The surface-modified metal oxide nanoparticles have an average particle size that
10 is smaller than the wavelength of light, for example, less than about 300 nm.

When used, the surface-modified metal oxide nanoparticles may be present in an amount greater than one-half the source of the organopolysiloxane precursors on a weight basis. With respect to the bonding layer that forms from bonding the LED die and the optical element together, the surface-modified metal oxide nanoparticles may be present in
15 an amount of from about 1 to about 95% by weight relative to the weight of the bonding layer. Typically, it is desirable to have from about 40 to about 95% by weight of the surface-modified metal oxide nanoparticles relative to the total weight of the bonding layer. The particular amount used is partly determined by the desired refractive index for the bonding layer as described below. If the amount of the nanoparticles in the bonding
20 layer is too great, however, it is difficult to obtain suitable bonding between the LED die and the optical element, and in addition, efficiency of the LED light source may suffer.

In particular, the surface-modified metal oxide nanoparticles comprise highly crystalline zirconia nanoparticles having a refractive index of at least about 1.8, preferably at least about 2.0, such as the nanoparticles described in U.S. 6,376,590 B2, the disclosure
25 of which is incorporated herein by reference. The highly crystalline zirconium oxide nanoparticles may be incorporated into the optical composition by surface modification with one or more of the alkoxysilanes described above for the formula A-B. The highly crystalline zirconium oxide nanoparticles may be incorporated into the optical composition by surface modification with one or more of the carboxylic acids described
30 above for the formula A-B. The highly crystalline zirconium oxide nanoparticles have an average particle size of less than about 100 nm.

The refractive index of the zirconia nanoparticles described above is much higher than that of amorphous zirconia. When incorporated into the silicate network to give an amorphous silicate network, the zirconia nanoparticles provide an increase in the refractive index of the bonding layer. Thus, the optical properties of the bonding layer
5 may be tailored as described below, depending on the particular LED die and optical element to be bonded. In particular, the refractive index of the silicate network is about 1.4, and for the surface-modified zirconium oxide nanoparticles is from about 1.8 to about 2.1. The surface-modified metal oxide nanoparticles may also comprise crystalline titanium oxide nanoparticles having a refractive index of greater than about 2.0, and
10 preferably greater than about 2.2.

The efficiency of the LED light source is directly related to the extent to which the LED die and the optical element are optically coupled. It should be noted that throughout the disclosure, reference to the refractive index of the LED die is a reference to the refractive index of a light emission layer of the LED die. The extent to which the LED die
15 and the optical element are optically coupled depends on several factors including the thickness of the bonding layer and the refractive indices of the bonding layer, the LED die, and the optical element. In general, the refractive index of the bonding layer is less critical to optical coupling between the LED die and the optical element when the thickness of the bonding layer is substantially less than the wavelength of the emission
20 light in air, for example, less than about 50 nm. As thickness increases, the refractive index of the bonding layer becomes increasingly critical with respect to optical coupling.

The bonding layer may have a thickness of less than 50 nm, but it is usually greater than about 50 nm, for example, up to about 200 nm or 300 nm, or even up to 10 μ m or 100 μ m. The bonding layer may have a thickness of from about 5 nm to about 300 nm, or
25 from greater than about 50 nm to about 100 μ m. To optimize optical coupling between the LED die and the optical element, the thickness of the bonding layer is desirably substantially uniform over the area of contact between the first and second surfaces. The minimum necessary thickness of the bonding layer may depend on the flatness or irregularities of the surfaces to be bonded.

30 In order to maximize efficiency, the refractive index of the bonding layer is closely matched to that of the light emission surface of the LED die (or light emission layer as described above), for example, within about 0.2. If the refractive index of the bonding

layer is too low, light emitted by the LED die becomes trapped in the die and is lost to absorption even if the bonding layer itself is nonabsorbing. By increasing the refractive index of the bonding layer to that of the light emission layer, a larger fraction of light emitted by the LED may be coupled out of the die and into the optical element, even if the
 5 bonding layer absorbs a portion of the emitted light.

As described above, the refractive index of the LED die, or light emission layer, ranges from about 1.7 to about 4.1 at the emission wavelength of the LED die. The refractive index of the amorphous organopolysiloxane network without the surface-modified metal oxide nanoparticles is greater than about 1.4. The surface-modified metal
 10 oxide nanoparticles are used to increase the refractive index up to about 2.4. In one example, the refractive index of the bonding layer is at least about 1.5, for example, greater than about 1.8, or greater than about 2, at the emission wavelength of the LED die.

In a particular example, the LED die comprises a light emitting layer having a refractive index of greater than 1.9, and the bonding layer has a thickness of from about 50
 15 nm to about 100 μm . In another example, the LED die comprises a light emitting layer having a refractive index of less than or equal to 1.9, and the bonding layer has a thickness of from greater than about 5 nm to about 300 nm.

The bonding layer is substantially transparent to the particular wavelength of light emitted by the LED die. In most cases, at least about 70% transmission is desirable and
 20 may be obtained by optimization of transmission path length (bonding layer thickness) and absorption constant.

Also disclosed herein is a method of making an LED light source, the method comprising: a) providing an LED die; b) providing an optical element; c) providing an optical bonding composition comprising a silsesquioxane having the formula
 25 $(\text{R}^1\text{SiO}_{1.5})_n(\text{OR}^4)_{n+2}$ and a dialkoxysilane having the formula $(\text{R}^2)_2\text{Si}(\text{OR}^3)_2$ wherein R^1 to R^4 are organic groups and n is an integer of at least 5; and a dialkoxysilane having the formula $(\text{R}^2)_2\text{Si}(\text{OR}^3)_2$; and d) bonding the LED die and the optical element together by contacting the LED die and the optical element with the optical bonding composition.

The optical composition may be applied to one or more surfaces of either the LED
 30 die, the optical element, or both, using a pipette, or by dip coating, spin coating, aerosol dispensing, pouring, dispersing, spraying under water, or by joining the surfaces in a bath of the optical composition, or by other similar methods. The surfaces are then brought

into contact to sandwich the optical composition such that the composition spreads across each of the surfaces and forms a homogenous layer. If bubbles form, they may be removed by application of a vacuum. The assembly is then allowed to stand at room temperature until it is handleable without bond failure; this may be from several minutes to several days. An external compressive force or vacuum may be used to accelerate the bonding process and/or to promote good bonding.

Heat may be applied to accelerate formation of and/or strengthen the bonding layer, however, the temperature of the assembly must remain below the lowest glass transition temperature of any of the components. Temperatures less than about 300°C are typically used, for example, less than about 200°C, or less than or equal to 150°C. It is desirable that the lowest possible temperature be used in order to minimize residual stress and birefringence at the interface caused by the difference in the coefficient of thermal expansion of the LED die and the optical element. In some cases, care must be taken such that the temperature of the bonding layer does not exceed the temperature that would be reached during operation of the light source.

The optical bonding composition may also be used as an encapsulant for an LED light source. The encapsulant is in contact with and encapsulates the LED die.

The encapsulant may comprise the reacted optical bonding composition such that the encapsulant comprises an amorphous organopolysiloxane network, the organopolysiloxane network comprising a silsesquioxane portion derived from $(R^1SiO_{1.5})_n$, wherein R^1 is an organic group and n is an integer of at least 10.

The LED light source would be made by the method comprising: a) providing an LED die; b) providing any of the optical bonding compositions described herein; c) contacting the LED die with any of the compositions provided in b), thereby forming an assembly; and d) optionally heating the assembly.

EXAMPLE

Surface-modified zirconium oxide nanoparticles were prepared as follows. 100g of 23% by weight zirconia sol (25.5% by weight solids in water, the solids being zirconium oxide and acetic acid); 100g of 1-methoxy-2-propanol; and 5.45g of 2-[2-(2-methoxyethoxy) ethoxy] acetic acid (MEEAA) were combined to give a mixture having 1.2 mmol of MEEAA per g of zirconium oxide). The mixture was placed on a rotary

evaporator to remove the solvents. A dried solid was obtained and was further dried in a vacuum oven for about 12 hours at 60°C. The resulting dry powder was dispersed in 229.5g of methanol to form a translucent liquid having 12% by weight nanoparticles.

5 An siloxane solution comprising 50g of poly(phenyl siloxane ($\text{C}_6\text{H}_5\text{SiO}_{1.5}\text{}$)_x glass resin flake (GR-950 from Techneglas) and 115g of acetone was prepared by swirling the two components for 30 minutes until a clear solution was obtained.

A mixture was prepared by combining 10g of the nanoparticle solution, 0.43g of the siloxane solution and 0.3g of diphenyldimethoxysilane. The optical bonding composition, a viscous translucent material, was obtained upon removal of solvents using
10 a rotary evaporator.

Optical glasses (LAH-51 and LAH-66, both from O'Hara Corp.) and a non-polished sapphire substrate (from Rubicon Technology) were cleaned ultrasonically for 11 minutes in acetone followed by 11 minutes in ethanol. The cleaned surfaces were allowed to dry.

15 The optical bonding composition was then used to bond each optical glass to a sapphire substrate. The optical bonding composition was applied to a surface of the optical glass and a piece of sapphire substrate was brought into contact with the optical bonding composition. A moderate pressure was applied for 10 seconds. The joined sample was allowed to sit at room temperature for 24 hours. The joined sample was then
20 heated to 80°C for 4 hours, followed by heating at 120°C for 4 hours.

After cooling to room temperature, the bond strength for each assembly was high enough to allow for handling without fracture of the newly formed bond between the glass and the sapphire.

25 Encapsulation of an LED with the optical bonding composition

Into a Kyocera ceramic package with electrodes (Kyocera America, Inc., Part No. KD-LA2707-A) was bonded a Cree XT die (Cree Inc., Part No. C460XT290-0119-A) using a water based halide flux (Superior No. 30, Superior Flux & Mfg. Co.). The LED package was completed by wire bonding (Kulicke and Soffa Industries, Inc. 4524 Digital
30 Series Manual Wire Bonder) the Cree XT die using 1 mil gold wire. Prior to use each package was tested without encapsulation using a OL 770 Spectroradiometer (Optronics Laboratories, Inc.) with a constant current of 20 mA.

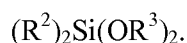
Into the Kyocera LED package (emission maximum ~460 nm) is placed approximately 2 milligrams (mg) of the optical bonding composition. The LED package with uncured encapsulant compositions is heated for 4 hours at 80 °C followed by heating at 120 °C for 4 hours. The cured encapsulant is cured as determined by probing with the
5 tip of a tweezer. The efficiency of the LED is measured using an OL 770 spectroradiometer and is increased relative to the LED prior to encapsulation.

Various modifications and alterations of the invention will become apparent to those skilled in the art without departing from the spirit and scope of the invention. It
10 should be understood that the invention is not intended to be unduly limited by the illustrative embodiments and examples set forth herein, and that such examples and embodiments are presented by way of example only with the scope of the invention intended to be limited only by the claims set forth herein as follows.

What is claimed is:

1. An LED light source comprising:
an LED die;
5 an optical element optically coupled to the LED die; and
a bonding layer comprising an amorphous organopolysiloxane network, the
organopolysiloxane network comprising a silsesquioxane portion derived from

$$(R^1SiO_{1.5})_n$$
wherein R^1 is an organic group and n is an integer of at least 10;
10 the bonding layer bonding the LED die and the optical element together.
2. The LED light source of claim 1, wherein n is an integer of at least 20.
3. The LED light source of claim 1, wherein R^1 is an alkyl, alkylaryl, arylalkyl, or aryl
15 group.
4. The LED light source of claim 1, wherein R^1 is a methyl, ethyl, propyl, phenyl or
naphthyl group.
- 20 5. The LED light source of claim 1, the bonding layer comprising at least about 5% by
weight of the silsesquioxane portion.
6. The LED light source of claim 1, the bonding layer comprising at least about 20% by
weight of the silsesquioxane portion.
- 25 7. The LED light source of claim 1, the bonding layer comprising at least about 40% by
weight of the silsesquioxane portion.
8. The LED light source of claim 1, the amorphous organopolysiloxane network being
30 derived essentially from D-units, the D-units comprising:



9. The LED light source of claim 8, wherein $R^1 = R^2$.
10. The LED light source of claim 8, wherein R^2 is methyl or phenyl.
- 5 11. The LED light source of claim 1, the bonding layer further comprising surface-modified metal oxide nanoparticles.
- 10 12. The LED light source of claim 11, the surface-modified metal oxide nanoparticles comprising metal oxide nanoparticles selected from the group consisting of zirconium oxide, titanium oxide, zinc oxide, tantalum oxide, niobium oxide, lanthanum oxide, strontium oxide, yttrium oxide, hafnium oxide, tin oxide, antimony oxide, and combinations thereof.
- 15 13. The LED light source of claim 11, the surface-modified metal oxide nanoparticles comprising mixed metal oxide nanoparticles of at least two metal oxides selected from the group consisting of silicon oxide, aluminum oxide, zirconium oxide, titanium oxide, zinc oxide, tantalum oxide, niobium oxide, lanthanum oxide, strontium oxide, yttrium oxide, hafnium oxide, tin oxide, antimony oxide, and combinations thereof.
- 20 14. The LED light source of claim 13, the mixed metal oxide nanoparticles comprising silicon oxide and zirconium oxide.
- 25 15. The LED light source of claim 13, the mixed metal oxide nanoparticles comprising silicon oxide and titanium oxide.
- 30 16. The LED light source of claim 13, the mixed metal oxide nanoparticles comprising silicon oxide, zirconium oxide, and titanium oxide.

17. The LED light source of claim 11, the surface-modified metal oxide nanoparticles comprising crystalline zirconium oxide nanoparticles having a refractive index of greater than about 1.8.
- 5 18. The LED light source of claim 11, the surface-modified metal oxide nanoparticles comprising crystalline titanium oxide nanoparticles having a refractive index of greater than about 2.0.
- 10 19. The LED light source of claim 11, the surface-modified metal oxide nanoparticles being surface-modified with a surface-modifier, the surface-modifier comprising a carboxylic acid, a phosphonic acid, an alkoxysilane, or a combination or mixture thereof.
- 15 20. The LED light source of claim 19, the carboxylic acid comprising a polyethyleneglycol carboxylic acid.
21. The LED light source of claim 11, the bonding layer comprising from about 40 to about 95% by weight of the surface-modified metal oxide nanoparticles.
- 20 22. The LED light source of claim 1, the LED die comprising a light emitting layer having a refractive index of greater than 1.9, and the bonding layer having a thickness of from about 50 nm to about 100 um.
- 25 23. The LED light source of claim 1, the LED die comprising a light emitting layer having a refractive index of less than or equal to 1.9, and the bonding layer having a thickness of from greater than about 5 nm to about 300 nm.
- 30 24. The LED light source of claim 1, wherein the LED die comprises a light emitting surface, the optical element comprises a light input surface, and the bonding layer bonds the light emitting surface and the light input surface together.

25. The LED light source of claim 1, the optical element having a refractive index of at least about 2.0.
26. The LED light source of claim 1, the optical element comprising an optical glass
5 having a refractive index of at least about 1.7.
27. The LED light source of claim 1, the optical element comprising a diverging or converging extractor.
- 10 28. A method of making an LED light source, the method comprising:
a) providing an LED die;
b) providing an optical element;
c) providing an optical bonding composition comprising a silsesquioxane having the
formula $(R^1SiO_{1.5})_n(OR^4)_{n+2}$ and a dialkoxysilane having the formula
15 $(R^2)_2Si(OR^3)_2$, wherein R^1 to R^4 are organic groups and n is an integer of at least
5; and
d) bonding the LED die and the optical element together by contacting the LED die
and the optical element with the optical bonding composition.
- 20 29. The method of claim 28, wherein an assembly is formed from bonding the LED die
and the optical element together, and the method further comprises heating the
assembly.
30. The method of claim 28, the optical bonding composition further comprising
25 surface-modified metal oxide nanoparticles.
31. The LED light source of claim 30, the surface-modified metal oxide nanoparticles
comprising crystalline zirconium oxide nanoparticles having a refractive index of
greater than about 1.8.
- 30 32. An optical bonding composition comprising:
surface-modified metal oxide nanoparticles;

a silsesquioxane having the formula $(R^1SiO_{1.5})_n(OR^4)_{n+2}$; and
a dialkoxysilane having the formula $(R^2)_2Si(OR^3)_2$, wherein R^1 to R^4 are organic groups and n is an integer of at least 5.

- 5 33. The optical bonding composition of claim 32, the surface-modified metal oxide nanoparticles comprising metal oxide nanoparticles selected from the group consisting of zirconium oxide, titanium oxide, zinc oxide, tantalum oxide, niobium oxide, lanthanum oxide, strontium oxide, yttrium oxide, hafnium oxide, tin oxide, antimony oxide, and combinations thereof.
- 10 34. The optical bonding composition of claim 32, the surface-modified metal oxide nanoparticles comprising mixed metal oxide nanoparticles of at least two metal oxides selected from the group consisting of silicon oxide, aluminum oxide, zirconium oxide, titanium oxide, zinc oxide, tantalum oxide, niobium oxide,
- 15 lanthanum oxide, strontium oxide, yttrium oxide, hafnium oxide, tin oxide, antimony oxide, and combinations thereof.
- 20 35. The optical bonding composition of claim 32, the surface-modified metal oxide nanoparticles comprising crystalline zirconium oxide nanoparticles having a refractive index of greater than about 1.8.
- 25 36. The optical bonding composition of claim 35, wherein the surface-modified metal oxide nanoparticles are present in an amount greater than one-half the source of the organopolysiloxane precursors on a weight basis.
- 30 37. The optical bonding composition of claim 32, further comprising an acid.
38. An LED light source comprising:
an LED die; and
an encapsulant in contact with and encapsulating the LED die, the encapsulant comprising the optical bonding composition of claim 32.

39. The LED light source of claim 38, the encapsulant having a refractive index of greater than about 1.6.
40. The LED light source of claim 38, wherein R^1 and R^2 are phenyl groups.
- 5 41. The LED light source of claim 38, wherein the surface-modified metal oxide nanoparticles comprise crystalline zirconium oxide nanoparticles having a refractive index of greater than about 1.8.
- 10 42. The LED light source of claim 38, the surface-modified metal oxide nanoparticles being surface-modified with a surface-modifier, the surface-modifier comprising a polyethyleneglycol carboxylic acid.
43. An LED light source comprising:
- 15 an LED die; and
an encapsulant in contact with and encapsulating the LED die, the encapsulant comprising an amorphous organopolysiloxane network, the organopolysiloxane network comprising a silsesquioxane portion derived from
- $$(R^1SiO_{1.5})_n$$
- 20 wherein R^1 is an organic group and n is an integer of at least 10.
44. The LED light source of claim 43, the encapsulant comprising surface-modified metal oxide nanoparticles, the surface-modified metal oxide nanoparticles comprising crystalline zirconium oxide nanoparticles having a refractive index of
- 25 greater than about 1.8.
45. The LED light source of claim 43, the amorphous organopolysiloxane network being derived essentially from D-units, the D-units comprising:
- $$(R^2)_2Si(OR^3)_2.$$
- 30

46. The LED light source of claim 45, the encapsulant comprising surface-modified metal oxide nanoparticles, the surface-modified metal oxide nanoparticles comprising crystalline zirconium oxide nanoparticles having a refractive index of greater than about 1.8.

5

47. A method of making an LED light source, the method comprising:
- a) providing an LED die;
 - b) providing any of the optical bonding compositions described herein;
 - c) contacting the LED die with any of the compositions provided in b), thereby
- 10 forming an assembly; and
- d) optionally heating the assembly.

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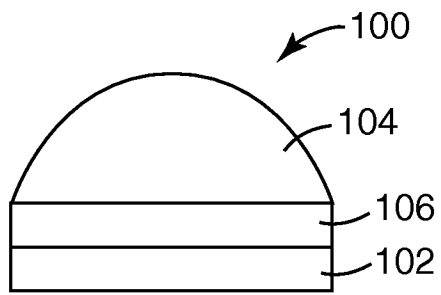


Fig. 1

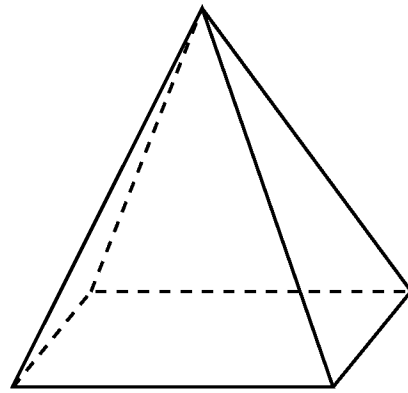


Fig. 2a

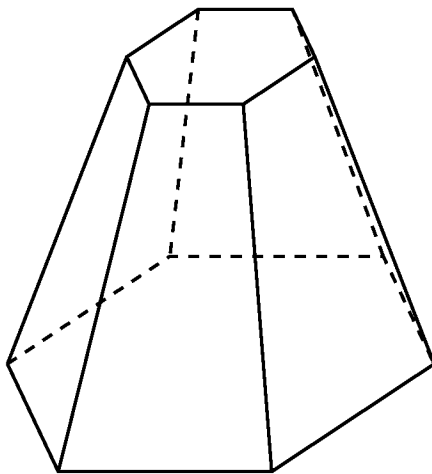


Fig. 2b

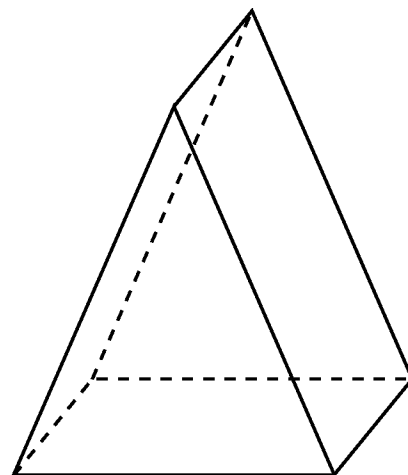


Fig. 2c

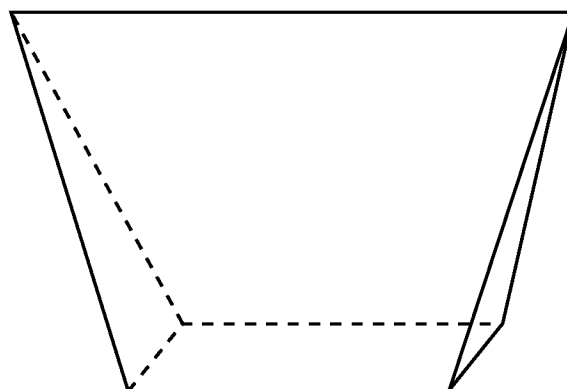


Fig. 2d

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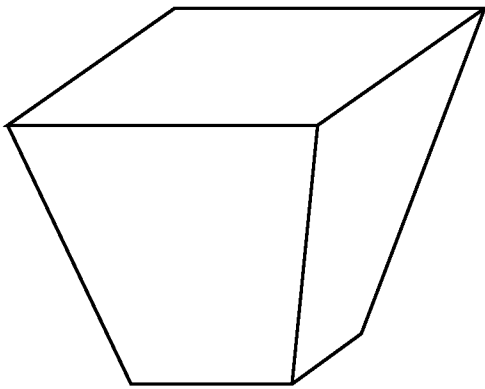


Fig. 3a

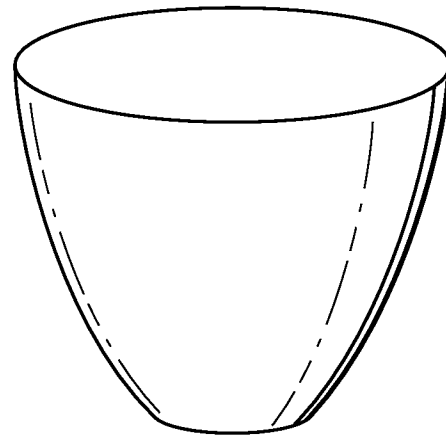


Fig. 3b

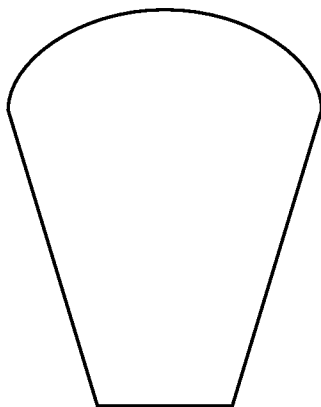


Fig. 3c

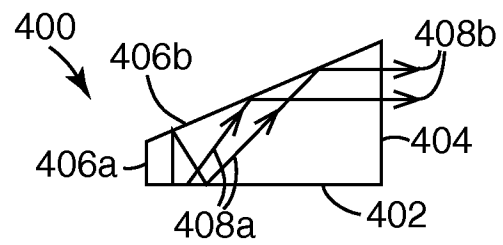


Fig. 4A

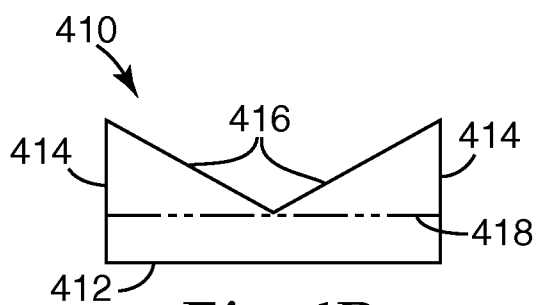


Fig. 4B

A. CLASSIFICATION OF SUBJECT MATTER***H01L 33/00(2006.01)i, F21S 8/04(2006.01)i***

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

IPC8 H01L, C09J

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Korean Utility models and applications for Utility models since 1975

Japanese Utility models and application for Utility models since 1975

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

eKIPASS(KIPO internal) "optical bonding composition", "organopolysiloxane"

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
Y	WO 2004/077580 A2 (CREE, INC.) 10 Sep. 2004 See Abstract; Figures 1-12	1-7, 11-19, 21-27, 43, 44, 47
Y	JP 13-139894 A (DOW CORNING TORAY SILICONE CO., LTD.) 22 May 2001 See Abstract; Paragraph [0007]-Paragraph [0033]	1-7, 11-19, 21-27, 43, 44, 47
A	JP 09-296113 A (DOW CORNING TORAY SILICONE CO., LTD.) 18 Nov. 1997 See Abstract; Claims 1-4	1-47
A	US 6806509 B2 (YOSHINO et al.) 19 Oct. 2004 See Abstract; Column 9, Line 42-Column 9, Line 65; Figures 1-3	1-47



Further documents are listed in the continuation of Box C.



See patent family annex.

* Special categories of cited documents:

"A" document defining the general state of the art which is not considered to be of particular relevance

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"L" document which may throw doubts on priority claim(s) or which is cited to establish the publication date of citation or other special reason (as specified)

"O" document referring to an oral disclosure, use, exhibition or other means

"P" document published prior to the international filing date but later than the priority date claimed

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"X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone

"Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art

"&" document member of the same patent family

Date of the actual completion of the international search

28 MARCH 2008 (28.03.2008)

Date of mailing of the international search report

28 MARCH 2008 (28.03.2008)

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Authorized officer

LEE, Jin Hong

Telephone No. 82-42-481-8509



INTERNATIONAL SEARCH REPORT

Information on patent family members

International application No.

PCT/US2007/083874

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